

inorganic filler and a thermosetting resin, which is formed on at least one surface of the core layer; and a plurality of wiring patterns formed of a copper foil; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns are connected electrically to each other by the inner vias.

6. (Amended) The component built-in module according to claim 1, comprising a core layer formed of an electric insulating material; an electric insulating layer comprising an insulating material formed of a thermosetting resin, which is formed on at least one surface of the core layer; and a plurality of wiring patterns formed by copper-plating; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns formed by the copper-plating are connected electrically to each other by the inner vias.

7. (Amended) The component built-in module according to claim 1, comprising a core layer formed of an electric insulating material; an electric insulating layer formed of an organic film having thermosetting resins on both surfaces, which is formed on at least one surface of the core layer; and a plurality of wiring patterns formed of a copper foil; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns are connected electrically to each other by the inner vias.

8. (Amended) The component built-in module according to claim 1, comprising a core layer formed of an electric insulating material; and a ceramic substrate having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin.

9. (Amended) The component built-in module according to claim 1, comprising a core layer formed of an electric insulating material; and a plurality of ceramic substrates having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin; and the plurality of ceramic substrates comprise dielectric materials having different dielectric constants.

10. (Amended) The component built-in module according to claim 1, wherein a film-shaped passive component is disposed between the wiring patterns formed on at least one surface of the core layer.

17. (Amended) The method for producing the component built-in module according to claim 14, wherein the film-shaped component is at least one selected from the group consisting of a resistor, a capacitor and an inductor, which is formed of a thin film or a mixture comprising an inorganic filler and a thermosetting resin; and the film-shaped component is formed by one method

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selected from the group consisting of vapor deposition method, MO-CVD method or a thick film printing method.

Please add the following new claims:

22. (New) The method for producing the component built-in module according to claim 16, wherein the film-shaped component is at least one selected from the group consisting of a resistor, a capacitor and an inductor, which is formed of a thin film or a mixture comprising an inorganic filler and a thermosetting resin; and the film-shaped component is formed by one method selected from the group consisting of vapor deposition method, MO-CVD method or a thick film printing method.

23. (New) The component built-in module according to claim 2, comprising a through hole that extends through all of the core layer, the electric insulating layer and the wiring pattern.

24. (New) The component built-in module according to claim 3, comprising a through hole that extends through all of the core layer, the electric insulating layer and the wiring pattern.

25. (New) The component built-in module according to claim 2, comprising a core layer formed of an electric insulating material; an electric insulating layer comprising an electric insulating material formed of a mixture including an inorganic filler and a thermosetting resin, which is formed on at least one surface

of the core layer; and a plurality of wiring patterns formed of a copper foil; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns are connected electrically to each other by the inner vias.

26. (New) The component built-in module according to claim 3, comprising a core layer formed of an electric insulating material; an electric insulating layer comprising an electric insulating material formed of a mixture including an inorganic filler and a thermosetting resin, which is formed on at least one surface of the core layer; and a plurality of wiring patterns formed of a copper foil; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns are connected electrically to each other by the inner vias.

27. (New) The component built-in module according to claim 2, comprising a core layer formed of an electric insulating material; an electric insulating layer comprising an insulating material formed of a thermosetting resin, which is formed on at least one surface of the core layer; and a plurality of wiring patterns formed by copper-plating; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin, and the wiring patterns formed by the copper-plating are connected electrically to each other by the inner vias.

31. (New) The component built-in module according to claim 2, comprising a core layer formed of an electric insulating material; and a ceramic substrate having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin.

32. (New) The component built-in module according to claim 3, comprising a core layer formed of an electric insulating material; and a ceramic substrate having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin.

33. (New) The component built-in module according to claim 2, comprising a core layer formed of an electric insulating material; and a plurality of ceramic substrates having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin; and the plurality of ceramic substrates comprise dielectric materials having different dielectric constants.

34. (New) The component built-in module according to claim 3, comprising a core layer formed of an electric insulating material; and a plurality of ceramic substrates having a plurality of wiring patterns and inner vias adhered onto at least one surface of the core layer; wherein the core layer has a plurality of wiring

patterns formed of a copper foil and a plurality of inner vias formed of a conductive resin; and the plurality of ceramic substrates comprise dielectric materials having different dielectric constants.

35. (New) The component built-in module according to claim 2, wherein a film-shaped passive component is disposed between the wiring patterns formed on at least one surface of the core layer.

36. (New) The component built-in module according to claim 3, wherein a film-shaped passive component is disposed between the wiring patterns formed on at least one surface of the core layer.

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